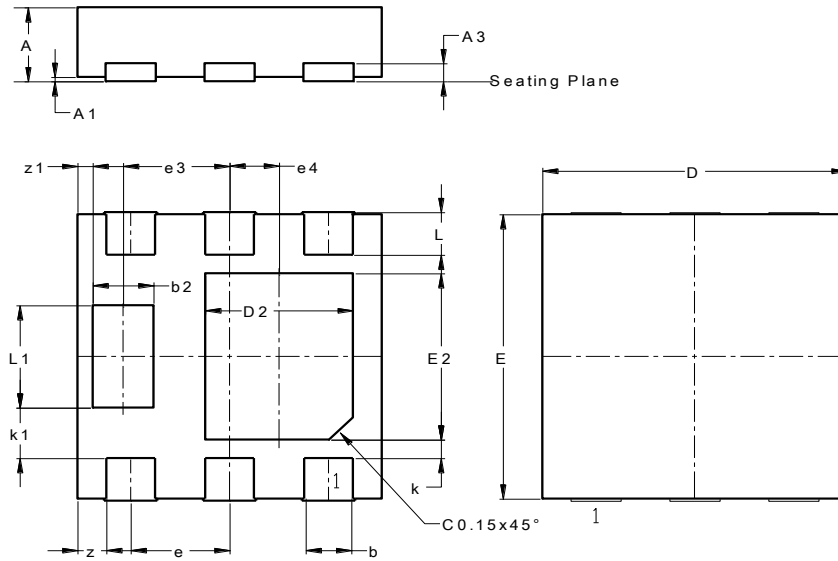


Package Outline Dimensions

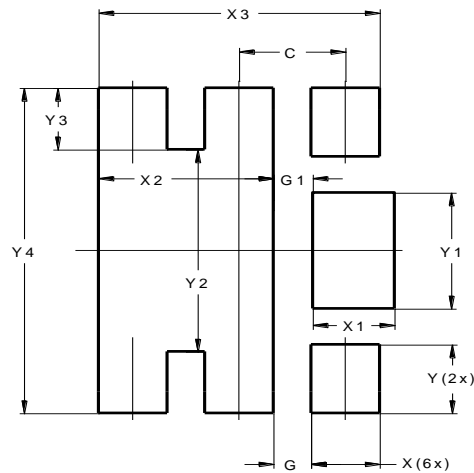
U-DFN2020-6/SWP (Type C)



U-DFN2020-6 (SWP) (Type C)			
Dim	Min	Max	Typ
A	0.47	0.57	0.52
A1	0.00	0.05	0.03
A3	--	--	0.127
b	0.27	0.37	0.32
b2	0.35	0.45	0.40
D	1.95	2.05	2.00
D2	0.87	1.07	0.97
E	1.95	2.05	2.00
E2	1.07	1.27	1.17
e	0.65 BSC		
e3	0.70 BSC		
e4	0.325 BSC		
k	--	--	0.13
k1	--	--	0.355
L	0.25	0.35	0.30
L1	0.67	0.77	0.72
z	--	--	0.19
z1	--	--	0.10
All Dimensions in mm			

Suggested Pad Layout

U-DFN2020-6/SWP (Type C)



Dimensions	Value (in mm)
C	0.650
G	0.230
G1	0.240
X	0.420
X1	0.500
X2	1.070
X3	1.720
Y	0.485
Y1	0.820
Y2	1.430
Y3	0.435
Y4	2.300

ALL DIMENSIONS ARE NOMINAL VALUES SHOWN IN MILLIMETERS

Note: The suggested land pattern dimensions have been provided for reference only, as actual pad layouts may vary depending on application. These numbers may be modified based on user equipment capability or fabrication criteria. A more robust pattern may be desired for wave soldering and is calculated by adding 0.2 mm to the 'Z' dimension. For further information, please reference document IPC-7351A, Naming Convention for Standard SMT Land Patterns, and for International grid details, please see document IEC, Publication 97.